# PhD in Mathematical Models for Engineering, Electromagnetics and Nanosciences XL Cycle



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Bachelor's degree: **Electronic Engineering** 

Master's degree: Nanotechnology Engineering

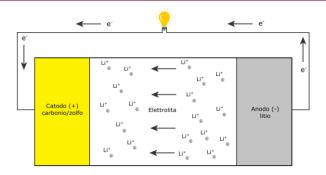
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## **Introduction and Project Goal**

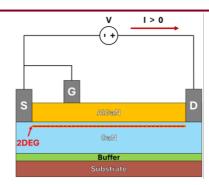
- **PhD Title**: Development of Nanostructured Materials and Correlative Microscopy Techniques for the Analysis and Optimization of Electrochemical and Semiconductor Devices
- Thesis Title: Carbon-Sulfur Nanostructured Composites for Electrochemical Storage
- Thesis Advisor: Prof. Leonardo Mattiello
- External Thesis Advisor: Dr. Nicola Lisi (Enea Casaccia Research Center)

**Specific Objective 1**: Increase the specific capacity of cathodes for Li-S batteries using Carbon NanoWalls (CNW) nanostructures.

**Specific Objective 2**: Develop correlative microscopy workflows to identify and characterize defects in GaN HEMT devices. (Leonardo S.p.A.)



Li-S Battery during Discharge Phase



GaN HEMT device



## **Project Idea:**

## Correlative Microscopy for Multiscale Characterization of Semiconductor Materials and Devices

**Combining Imaging Techniques**: Utilizing different imaging methods allows researchers to capture diverse data from a single sample, with light microscopy providing general morphology and electron microscopy revealing fine structural details.

**Enhanced Resolution and Information Depth**: Correlating data from various microscopy techniques achieves higher resolution and deeper understanding, essential for studying complex structures.

**Improved Contextual Understanding**: Correlative microscopy examines samples in their native context, offering a holistic view of spatial relationships between structural components.

**Comprehensive Chemical and Structural Analysis**: Techniques like EDX combined with electron microscopy provide detailed chemical composition analysis, enhancing material property understanding.

**Defect Analysis and Characterization**: Identifying and characterizing defects at various scales with different microscopy techniques helps understand the origins and impacts of these defects on material performance.



#### Methods and Results for Li-S Batteries

#### **Materials Used:**

- Carbon Paper (CP) as Substrate
- Growth of Carbon NanoWalls (CNW)
- Solid-Phase Sulfur Deposition

#### **Expected Results:**

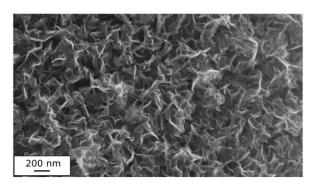
- Increase in Specific Capacity (ideal value: 1675 mAh/g)
- Improvement in Cycle Life and Stability
- Enhanced Reversibility of the Charge Cycle Relative to the Discharge Cycle

#### **Characterization Techniques:**

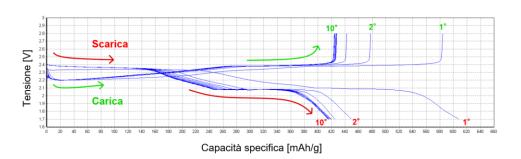
- Scanning Electron Microscopy (SEM) to Confirm the Presence of CNWs
- Galvanostatic Cycling to Analyze the Electrochemical Behavior of the Nanostructured Cathode

#### **Applications:**

 Electrical Energy Storage for Renewable Energy Storage (automotive, power grids, mobile electronic devices)



SEM Image of CNW Nanostructure at 80kx Magnification



Voltage Profile as a Function of Specific Capacity for the First 10 Cycles



# Correlative Microscopy for the Characterization of Nanostructured Cathodes in Li-S Batteries

**Goal:** Enhance the specific capacity of Li-S battery cathodes using Carbon NanoWalls (CNW) nanostructures.

**Detailed Morphological Analysis**: Correlative microscopy enables precise visualization of CNW nanostructures, aiding in understanding their morphology and distribution, which is crucial for optimizing cathode structure to increase specific capacity.

**Chemical Composition Mapping**: Combining techniques like SEM and EDX allows for detailed mapping of sulfur and carbon distribution within cathodes, ensuring uniform and efficient interaction between sulfur and CNWs, essential for battery performance.

**Performance Correlation**: By correlating microscopic data with electrochemical performance, researchers can identify structural features of CNWs that enhance battery capacity and efficiency, aiding in the design of better-performing cathodes.

**Identification of Structural Defects**: Correlative microscopy can reveal defects in CNWs that may affect battery performance. Understanding these defects can lead to improved synthesis processes and material quality, ultimately enhancing the battery's specific capacity.



#### Methods and Results for GaN HEMT

#### **Advantages of Correlative Microscopy:**

- Multiscale and Detailed Imaging of Samples in the Same Acquisition Area
- Morphological, Structural, and Compositional Characterization
- Precise Defect Identification

#### **Specific Objectives:**

- Identification of Defects in GaN HEMT Devices
- Correlation Between Microstructural Properties and Device Performance,
- Enhancement of Semiconductor Reliability and Performance

#### **Project Output:**

 Optimized Workflow for Failure Analysis and Defect Reports for Devices

#### **Applications:**

 Use in Electric Vehicles, Power Electronics Devices, and Advanced Communication Technologies



150 V GaN HEMT device



# Correlative Microscopy for the Characterization of GaN HEMT Devices

**Goal:** Develop workflows using correlative microscopy to identify and characterize defects in GaN HEMT (High Electron Mobility Transistor) devices.

**Comprehensive Defect Characterization**: Correlative microscopy provides detailed images of surface and subsurface defects. Techniques like AFM combined with SEM can identify and characterize defects impacting GaN HEMT device performance.

**High-Resolution Defect Imaging**: High-resolution techniques like TEM offer atomic-level images of defects within GaN crystals, crucial for understanding their nature and impact on device reliability and performance.

**In-Situ Defect Analysis**: Correlative microscopy allows for real-time monitoring of defects during device operation, aiding in understanding defect evolution under operational conditions, essential for improving device design and durability.

**Cross-Sectional Defect Analysis**: Using FIB combined with electron microscopy prepares cross-sectional samples of GaN HEMT devices, revealing hidden defects and their impact on different layers and interfaces.

